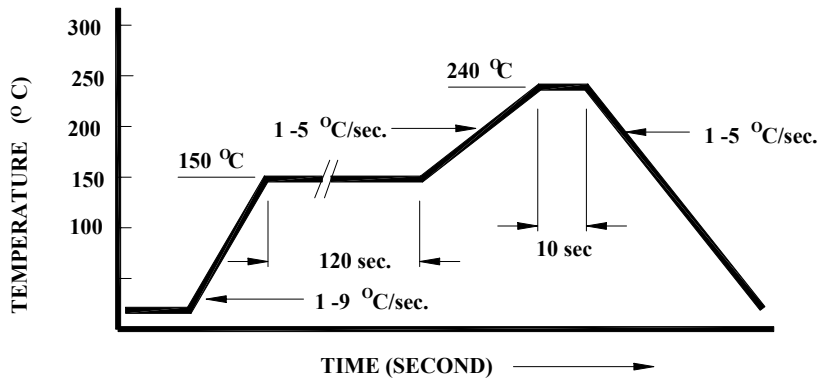




SMD Crystal Re-Flow Profile and Environmental Testing

I. Typical SMD solder re-flow profile

TYPICAL SMD CRYSTAL SOLDER RE-FLOW



II. Typical Environmental Specification for crystal

- A. Seal Integrity** Bubble test in Perfluorocarbon at $+125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 60 seconds minimum. (for hermetically sealed devices)
- B. Solderability** Sn63 solder at $+230^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5 seconds.
- C. Marking Permanency** 10 strokes with brush after 1 minute soak in solvent, 3 times.
- D. Shock** Random drop on hard wooden plate 3 times from height of 75 cm. (Call ILSI for specific devices)
- E. Thermal shock** 10 Cycles from -55°C to $+125^{\circ}\text{C}$
- F. Vibration** Frequency with amplitude of 1.5mm sweeping between 10Hz. to 55Hz. Within 1 minutes (approximately) for 2 hours minimum on each axis (X, Y, Z) for a total of 6 hours.

QVS TECH INC
6965 El Camino Real, Suite 105 Carlsbad, CA 92009
Phone: (760) 929-8677 Fax: (760) 929-8077
email: sales@qvstech.com

Specifications subject to change without notice